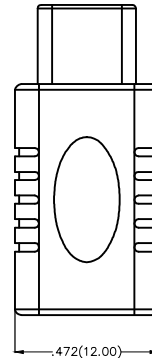
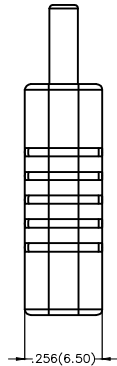
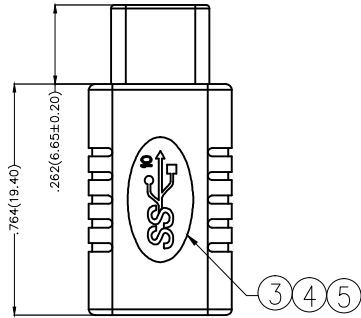
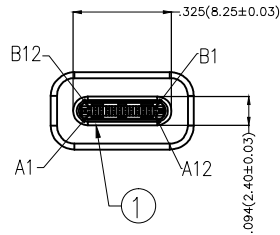


REV	LOCATIONS	DESCRIPTION	DATE	REVISER	APPD

Electrical

1. High voltage test: DC 300V/10MS
2. Conduction impedance: 5Ω (MAX)
3. Insulation Resistance: 10MΩ (MIN)

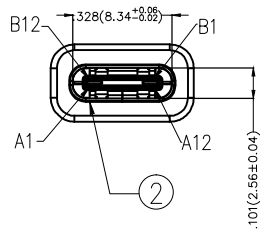
P1



PIN ASSIGNMENT

P1	P2	P1	P2
A1 ——— A1	B1 ——— B1		
A2 ——— A2	B2 ——— B2		
		ooooo	ooooo
A11 ——— A11	B11 ——— B11		
A12 ——— A12	B12 ——— B12		
		Shell ——— Shell	

P2



* Note: All Materials Meet The "RoHs" !

⑤	The outer mold: PVC glue 45P Black(Consumption: 2.1G)
④	Internal mold: PE glue transparent(Consumption: 1.5G)
③	PCB Board T=.031(0.80)
②	USB Type C/F Shell nickel plated, PIN Gold Plated
①	USB 3.1 C Type Male Shell nickel plated, PIN Gold Plated
NO.	Specification

 THIRD ANGLE PROJECTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		APPROVE BY	DATE	PART NO.	ITEM NO.	 Leader Of Industry
	X.±.020(0.50)	X.±5'	VERNON	21/JUN/17	FUS618-MDSK6B	FUS618	
DESIGN UNITS Inch (metric)	X.XX±.012(0.30)	.X'±2'	CHECKED BY	DATE	TITLE		REV 0 SHEET NO. 1/1
SCALE	X.XX±.008(0.20)	.XX'±1'	KATE	21/JUN/17	USB C-Type 180°Vertical Female+Male		
5:1	X.XXX±.004(0.10)	.XXX'±0.5'	DRAWN BY	DATE	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO TXGA INDUSTRIAL ELECTRONICS(S.Z)CO.,LTD AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		
SIZE			LXF	21/JUN/17			
A4							